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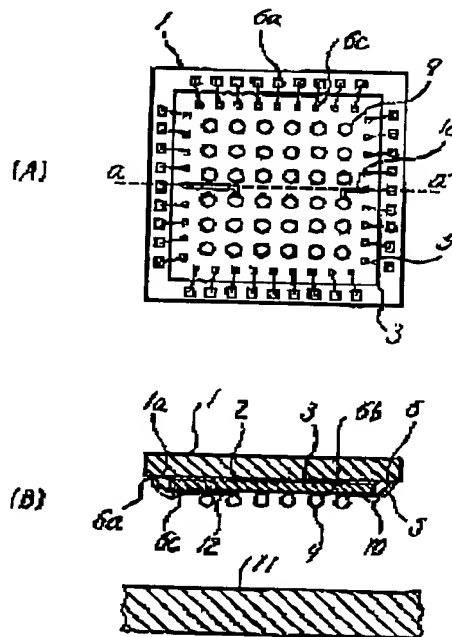
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## (54) ELECTRONIC PARTS ASSEMBLY BODY

## (57)Abstract:

PURPOSE: To reduce a bump distortion stress due to the difference in thermal coefficient of expansion and at the same time enhance the radiation effect of an LSI in flip-chip packaging.

CONSTITUTION: A carrier substrate 3 (a material whose thermal coefficient of expansion a middle value of LSI 1 and which has a high heat conductivity) is fixed on a circuit wiring surface 1a of the LSI 1 using a thermally conductive adhesive 2. A polyimide tape layer with a lead 5 is provided on the lower surface of a carrier substrate 3 and at an outer-periphery part and the lead 5 with Au bump 7 is alternately connected to an LSI electrode 6a from the inside of the polyimide tape and the outer-periphery part. Also, a lattice-shaped electrode pad 6b and a solder bump 9 are provided at the polyimide tape and are electrically connected to the LSI 1 via a through hole, a lead wire 5, Au bump, and LSI electrode 6a. Covering is made with molding resin 10 to protect the LSI 1 and the lead wire 5.



## LEGAL STATUS

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